

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Chopra et al. ) Group Art Unit 1765  
App. No. : 09/973,854 )  
Filed : October 9, 2001 )  
For : INLINE MONITORING OF )  
PAD LOADING FOR CuCMP )  
AND DEVELOPING AN )  
ENDPOINT TECHNIQUE )  
FOR CLEANING )  
Examiner : Unknown )

COPY OF PAPERS  
ORIGINALLY FILED

RECEIVED  
FEB 15 2002  
TC 1700

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Enclosed is form PTO-1449 listing references that are also enclosed. This Information Disclosure Statement is being filed within three months of the filing date of this application or upon filing if this is a CPA or RCE, and no fee is required in accordance with 37 C.F.R. § 1.97(b)(1), (b)(2), or (b)(4).

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: 1/8/02

By: [Signature]

Michael H. Trenholm  
Registration No. 37,743  
Attorney of Record  
620 Newport Center Drive  
Sixteenth Floor  
Newport Beach, CA 92660  
(909) 781-9231

FORM PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. MICRON.182A	APPLICATION NO. 09/973,854
<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  (USE SEVERAL SHEETS IF NECESSARY)		APPLICANT Chopra et al	<b>COPY OF PAPERS ORIGINALLY FILED</b>
		FILING DATE October 9, 2001	

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (IF APPROPRIATE)

## FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

EXAMINER INITIAL	OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)	
	A	Dinesh Chopra and Ian Ivar Suni, "An Optical Method for Monitoring Metal Contamination during Aqueous Processing of Silicon Wafers", <i>J. Electrochem. Soc.</i> , Vol. 145, No. 5, May 1998, pp. 1688-1692.
	B	Dinesh Chopra, Ian Ivar Suni and Ahmed A. Busnaina, "Cu Dissolution from Si(111) into an SC-1 Process Solution", <i>J. Electrochem. Soc.</i> , Vol. 145, No. 4, April 1998, pp. L60-61.
	C	Peter Singer, Editor-in-Chief, "Copper CMP: A Question of Tradeoffs", <i>Semiconductor International</i> , <a href="http://www.semiconductor.net/semiconductor/issues/issues/2000/200005/six0005cmp.asp">http://www.semiconductor.net/semiconductor/issues/issues/2000/200005/six0005cmp.asp</a> , May 2000, 11 pages.
	D	"The CMP Business Unit", Rodel Products, <a href="http://www.rodel.com/Products/CMP.asp">http://www.rodel.com/Products/CMP.asp</a> , 1998-2000, 13 pages.
	E	Kurt Hery and Dr. David P. Norwood, "Study of the Refractive Index Increment of Polyelectrolytes and Neutral Polymers", Southeastern Louisiana University, <a href="http://www.selu.edu/Academics/ArtsC/Sciences/connections/journal1/k-hery/Hery.html">http://www.selu.edu/Academics/ArtsC/Sciences/connections/journal1/k-hery/Hery.html</a> , 7 pages.
	F	Iqbal Ali and Sudipto R. Roy, "Pad conditioning in interlayer dielectric CMP", Texas Instruments, <a href="http://www.semipark.co.../Pad%20conditioning%20in%20interlayer%20dielectric%20CMP.ht">http://www.semipark.co.../Pad%20conditioning%20in%20interlayer%20dielectric%20CMP.ht</a> , June 1, 1997, 6 pages.
	G	"Chemical Mechanical Planarization (CMP)", S.C. Solutions, <a href="http://www.scsolutions.com/smp.html">http://www.scsolutions.com/smp.html</a> , 4 pages.

R:\DOCS\MHT\MHT-9724.DOC:lw  
010802

EXAMINER	DATE CONSIDERED
<b>*EXAMINER:</b> INITIAL IF CITATION CONSIDERED, WHETHER OR NOT CITATION IS IN CONFORMANCE WITH MPEP 609; DRAW LINE THROUGH CITATION IF NOT IN CONFORMANCE AND NOT CONSIDERED, INCLUDE COPY OF THIS FORM WITH NEXT COMMUNICATION TO APPLICANT.	

**RECEIVED**  
FEB 15 2002  
TC 1700